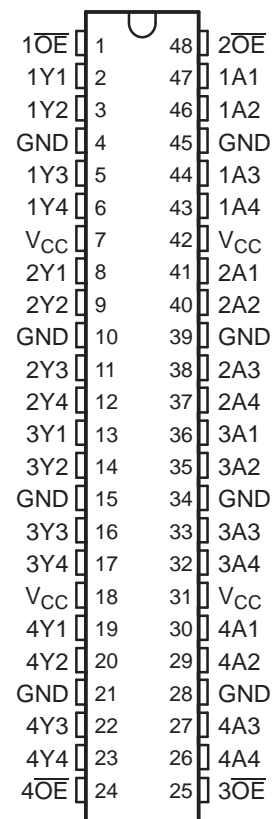


FEATURES

- Member of the Texas Instruments Widebus™ Family
- State-of-the-Art Advanced BiCMOS Technology (ABT) Design for 3.3-V Operation and Low Static-Power Dissipation
- Support Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V V_{CC})
- Support Unregulated Battery Operation Down to 2.7 V
- Typical V_{OLP} (Output Ground Bounce) <0.8 V at $V_{CC} = 3.3$ V, $T_A = 25^\circ\text{C}$
- I_{off} and Power-Up 3-State Support Hot Insertion
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

SN54LVT16244B . . . WD PACKAGE
SN74LVT16244B . . . DGG, DGV, OR DL PACKAGE
(TOP VIEW)



DESCRIPTION/ORDERING INFORMATION

ORDERING INFORMATION

T_A	PACKAGE ⁽¹⁾		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	FBGA – GRD	Reel of 1000	SN74LVT16244BGRDR	VD244B
	FBGA – ZRD (Pb-free)		SN74LVT16244BZRDR	
	SSOP – DL	Tube of 25	SN74LVT16244BDL	LVT16244B
			SN74LVT16244BDLG4	
		Reel of 1000	SN74LVT16244BDLR 74LVT16244BDLRG4	
	TSSOP – DGG	Reel of 2000	SN74LVT16244BDGGR	LVT16244B
			74LVT16244BDGGRG4	
	TVSOP – DGV	Reel of 2000	SN74LVT16244BDGVR	VD244B
			74LVT16244BDGVRE4	
	VFPGA – GQL	Reel of 1000	SN74LVT16244BGQLR	VD244B
SN74LVT16244BZQLR				
VFPGA – ZQL (Pb-free)	Reel of 1000	SN74LVT16244BZQLR	VD244B	
		SN74LVT16244BZQLR		
-55°C to 125°C	CFP – WD	Tube	SNJ54LVT16244BWD	SNJ54LVT16244BWD

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

Widebus is a trademark of Texas Instruments.

SN54LVT16244B, SN74LVT16244B 3.3-V ABT 16-BIT BUFFERS/DRIVERS WITH 3-STATE OUTPUTS

SCBS716E—MARCH 2000—REVISED DECEMBER 2006

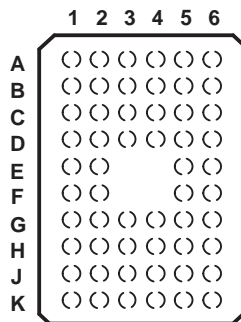
DESCRIPTION/ORDERING INFORMATION (CONTINUED)

The 'LVT16244B devices are 16-bit buffers and line drivers designed for low-voltage (3.3-V) V_{CC} operation, but with the capability to provide a TTL interface to a 5-V system environment. These devices can be used as four 4-bit buffers, two 8-bit buffers, or one 16-bit buffer. These devices provide true outputs and symmetrical active-low output-enable (\overline{OE}) inputs.

When V_{CC} is between 0 and 1.5 V, the devices are in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 1.5 V, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

These devices are fully specified for hot-insertion applications using I_{off} and power-up 3-state. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down. The power-up 3-state circuitry places the outputs in the high-impedance state during power up and power down, which prevents driver conflict.

**GQL OR ZQL PACKAGE
(TOP VIEW)**

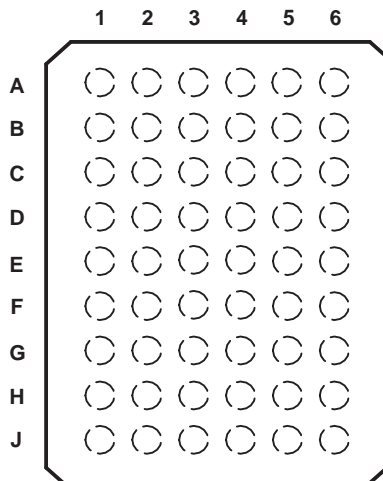


**TERMINAL ASSIGNMENTS⁽¹⁾
(56-Ball GQL/ZQL Package)**

	1	2	3	4	5	6
A	1 \overline{OE}	NC	NC	NC	NC	2 \overline{OE}
B	1Y2	1Y1	GND	GND	1A1	1A2
C	1Y4	1Y3	V_{CC}	V_{CC}	1A3	1A4
D	2Y2	2Y1	GND	GND	2A1	2A2
E	2Y4	2Y3			2A3	2A4
F	3Y1	3Y2			3A2	3A1
G	3Y3	3Y4	GND	GND	3A4	3A3
H	4Y1	4Y2	V_{CC}	V_{CC}	4A2	4A1
J	4Y3	4Y4	GND	GND	4A4	4A3
K	4 \overline{OE}	NC	NC	NC	NC	3 \overline{OE}

(1) NC – No internal connection

**GRD OR ZRD PACKAGE
(TOP VIEW)**



**TERMINAL ASSIGNMENTS⁽¹⁾
(54-Ball GRD/ZRD Package)**

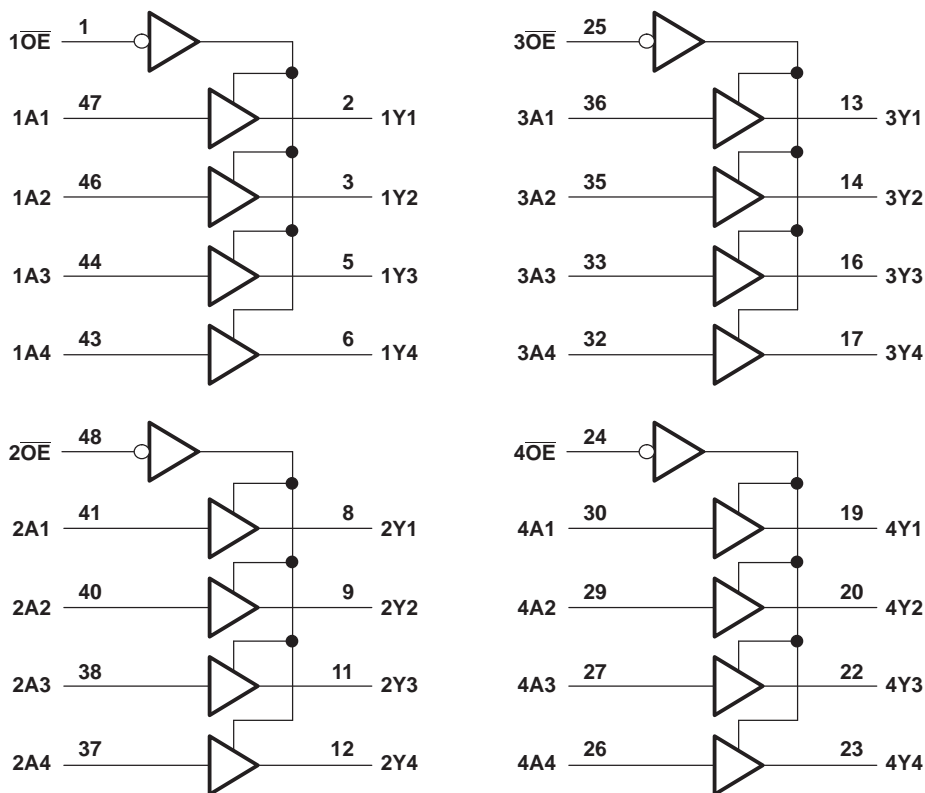
	1	2	3	4	5	6
A	1Y1	NC	1 \overline{OE}	2 \overline{OE}	NC	1A1
B	1Y3	1Y2	NC	NC	1A2	1A3
C	2Y1	1Y4	V_{CC}	V_{CC}	1A4	2A1
D	2Y3	2Y2	GND	GND	2A2	2A3
E	3Y1	2Y4	GND	GND	2A4	3A1
F	3Y3	3Y2	GND	GND	3A2	3A3
G	4Y1	3Y4	V_{CC}	V_{CC}	3A4	4A1
H	4Y3	4Y2	NC	NC	4A2	4A3
J	4Y4	NC	4 \overline{OE}	3 \overline{OE}	NC	4A4

(1) NC – No internal connection

**FUNCTION TABLE
(EACH 4-BIT BUFFER)**

INPUTS		OUTPUT Y
\overline{OE}	A	
L	H	H
L	L	L
H	X	Z

LOGIC DIAGRAM (POSITIVE LOGIC)



Pin numbers shown are for the DGG, DGV, DL, and WD packages.

SN54LVT16244B, SN74LVT16244B 3.3-V ABT 16-BIT BUFFERS/DRIVERS WITH 3-STATE OUTPUTS

SCBS716E—MARCH 2000—REVISED DECEMBER 2006

Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
V _{CC}	Supply voltage range	-0.5	4.6	V
V _I	Input voltage range ⁽²⁾	-0.5	7	V
V _O	Voltage range applied to any output in the high-impedance or power-off state ⁽²⁾	-0.5	7	V
V _O	Voltage range applied to any output in the high state ⁽²⁾	-0.5	V _{CC} + 0.5	V
I _O	Current into any output in the low state	SN54LVT16244B	96	mA
		SN74LVT16244B	128	
I _O	Current into any output in the high state ⁽³⁾	SN54LVT16244B	48	mA
		SN74LVT16244B	64	
I _{IK}	Input clamp current	V _I < 0	-50	mA
I _{OK}	Output clamp current	V _O < 0	-50	mA
θ _{JA}	Package thermal impedance ⁽⁴⁾	DGG package	70	°C/W
		DGV package	58	
		DL package	63	
		GQL/ZQL package	42	
		GRD/ZRD package	36	
T _{stg}	Storage temperature range	-65	150	°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.

(3) This current flows only when the output is in the high state and V_O > V_{CC}.

(4) The package thermal impedance is calculated in accordance with JESD 51-7.

Recommended Operating Conditions⁽¹⁾

		SN54LVT16244B ⁽²⁾		SN74LVT16244B		UNIT
		MIN	MAX	MIN	MAX	
V _{CC}	Supply voltage	2.7	3.6	2.7	3.6	V
V _{IH}	High-level input voltage	2		2		V
V _{IL}	Low-level input voltage		0.8		0.8	V
V _I	Input voltage		5.5		5.5	V
I _{OH}	High-level output current		-24		-32	mA
I _{OL}	Low-level output current		48		64	mA
Δt/Δv	Input transition rise or fall rate		10		10	ns/V
	Outputs enabled					
Δt/ΔV _{CC}	Power-up ramp rate	200		200		μs/V
T _A	Operating free-air temperature	-55	125	-40	85	°C

(1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

(2) Product preview

Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		SN54LVT16244B ⁽¹⁾			SN74LVT16244B			UNIT	
			MIN	TYP ⁽²⁾	MAX	MIN	TYP ⁽²⁾	MAX		
V_{IK}	$V_{CC} = 2.7\text{ V}$, $I_I = -18\text{ mA}$		-1.2			-1.2			V	
V_{OH}	$V_{CC} = 2.7\text{ to }3.6\text{ V}$, $I_{OH} = -100\text{ }\mu\text{A}$		$V_{CC} - 0.2$			$V_{CC} - 0.2$			V	
	$V_{CC} = 2.7\text{ V}$, $I_{OH} = -8\text{ mA}$		2.4			2.4				
	$V_{CC} = 3\text{ V}$	$I_{OH} = -24\text{ mA}$	2							
$I_{OH} = -32\text{ mA}$					2					
V_{OL}	$V_{CC} = 2.7\text{ V}$	$I_{OL} = 100\text{ }\mu\text{A}$				0.2			V	
		$I_{OL} = 24\text{ mA}$				0.5				
		$I_{OL} = 16\text{ mA}$				0.4				
	$V_{CC} = 3\text{ V}$	$I_{OL} = 32\text{ mA}$				0.5				
		$I_{OL} = 48\text{ mA}$				0.55				
		$I_{OL} = 64\text{ mA}$				0.55				
I_I	$V_{CC} = 0\text{ or }3.6\text{ V}$, $V_I = 5.5\text{ V}$		50			10			μA	
	Control inputs	$V_{CC} = 3.6\text{ V}$, $V_I = V_{CC}\text{ or GND}$		± 1			± 1			
		Data inputs	$V_{CC} = 3.6\text{ V}$	$V_I = V_{CC}$	1			1		
$V_I = 0$	-5			-5						
I_{off}	$V_{CC} = 0$, $V_I\text{ or }V_O = 0\text{ to }4.5\text{ V}$					± 100			μA	
I_{OZH}	$V_{CC} = 3.6\text{ V}$, $V_O = 3\text{ V}$		5			5			μA	
I_{OZL}	$V_{CC} = 3.6\text{ V}$, $V_O = 0.5\text{ V}$		-5			-5			μA	
I_{OZPU}	$V_{CC} = 0\text{ to }1.5\text{ V}$, $V_O = 0.5\text{ V to }3\text{ V}$, $\overline{OE} = \text{don't care}$		$\pm 100^{(3)}$			± 100			μA	
I_{OZPD}	$V_{CC} = 1.5\text{ V to }0$, $V_O = 0.5\text{ V to }3\text{ V}$, $\overline{OE} = \text{don't care}$		$\pm 100^{(3)}$			± 100			μA	
I_{CC}	$V_{CC} = 3.6\text{ V}$, $I_O = 0$, $V_I = V_{CC}\text{ or GND}$	Outputs high	0.19			0.19			mA	
		Outputs low	5			5				
		Outputs disabled	0.19			0.19				
$\Delta I_{CC}^{(4)}$	$V_{CC} = 3\text{ V to }3.6\text{ V}$, One input at $V_{CC} - 0.6\text{ V}$, Other inputs at $V_{CC}\text{ or GND}$		0.2			0.2			mA	
C_i	$V_I = 3\text{ V or }0$		4			4			pF	
C_o	$V_O = 3\text{ V or }0$		9			9			pF	

(1) Product preview

 (2) All typical values are at $V_{CC} = 3.3\text{ V}$, $T_A = 25^\circ\text{C}$.

(3) On products compliant to MIL-PRF-38535, this parameter is not production tested.

 (4) This is the increase in supply current for each input that is at the specified TTL voltage level, rather than V_{CC} or GND.

SN54LVT16244B, SN74LVT16244B

3.3-V ABT 16-BIT BUFFERS/DRIVERS

WITH 3-STATE OUTPUTS

SCBS716E—MARCH 2000—REVISED DECEMBER 2006

Switching Characteristics

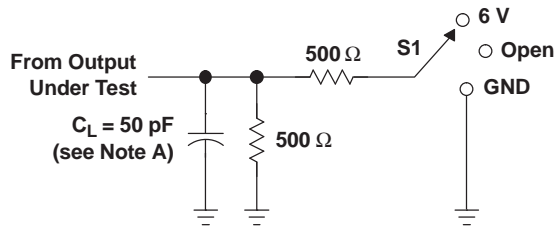
over recommended operating free-air temperature range, $C_L = 50$ pF (unless otherwise noted) (see [Figure 1](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54LVT16244B ⁽¹⁾				SN74LVT16244B				UNIT	
			$V_{CC} = 3.3$ V ± 0.3 V		$V_{CC} = 2.7$ V		$V_{CC} = 3.3$ V ± 0.3 V			$V_{CC} = 2.7$ V		
			MIN	MAX	MIN	MAX	MIN	TYP ⁽²⁾	MAX	MIN		MAX
t_{PLH}	A	Y	1.1	4.4		4.6	1.2	2.3	3.2		3.7	ns
t_{PHL}			1.1	3.6		3.9	1.2	2	3.2		3.7	
t_{PZH}	\overline{OE}	Y	1.1	4.6		5.4	1.2	2.6	4		5	ns
t_{PZL}			1.1	5.4		6.2	1.2	2.7	4		5	
t_{PHZ}	\overline{OE}	Y	1.6	5.7		6.2	2.2	3.3	4.5		5	ns
t_{PLZ}			1.2	5		4.7	2	3.1	4.2		4.4	
$t_{sk(LH)}$									0.5		ns	
$t_{sk(HL)}$									0.5			

(1) Product preview

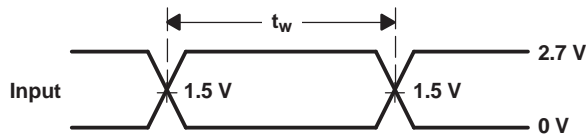
(2) All typical values are at $V_{CC} = 3.3$ V, $T_A = 25^\circ\text{C}$.

PARAMETER MEASUREMENT INFORMATION

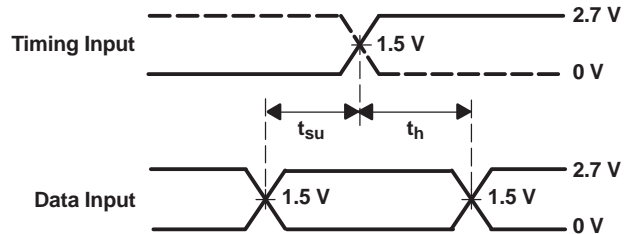


LOAD CIRCUIT

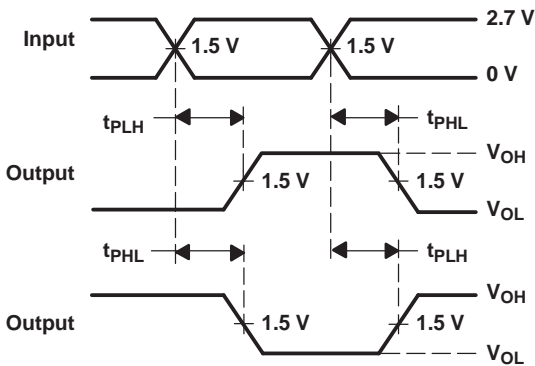
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	6 V
t_{PHZ}/t_{PZH}	GND



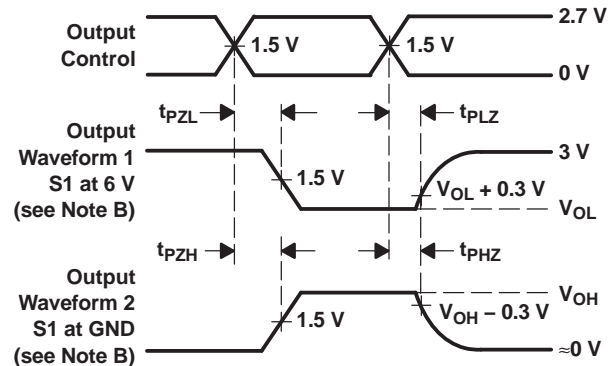
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
 D. The outputs are measured one at a time, with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
74LVT16244BDGGRG4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74LVT16244BDGVRE4	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74LVT16244BDGVRG4	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74LVT16244BDLRG4	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVT16244BDGGR	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVT16244BDGVR	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVT16244BDL	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVT16244BDLG4	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVT16244BDLR	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVT16244BGQLR	NRND	BGA MICROSTAR JUNIOR	GQL	56	1000	TBD	SNPB	Level-1-240C-UNLIM
SN74LVT16244BGRDR	ACTIVE	BGA MICROSTAR JUNIOR	GRD	54	1000	TBD	SNPB	Level-1-240C-UNLIM
SN74LVT16244BZQLR	ACTIVE	BGA MICROSTAR JUNIOR	ZQL	56	1000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM
SN74LVT16244BZRDR	ACTIVE	BGA MICROSTAR JUNIOR	ZRD	54	1000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

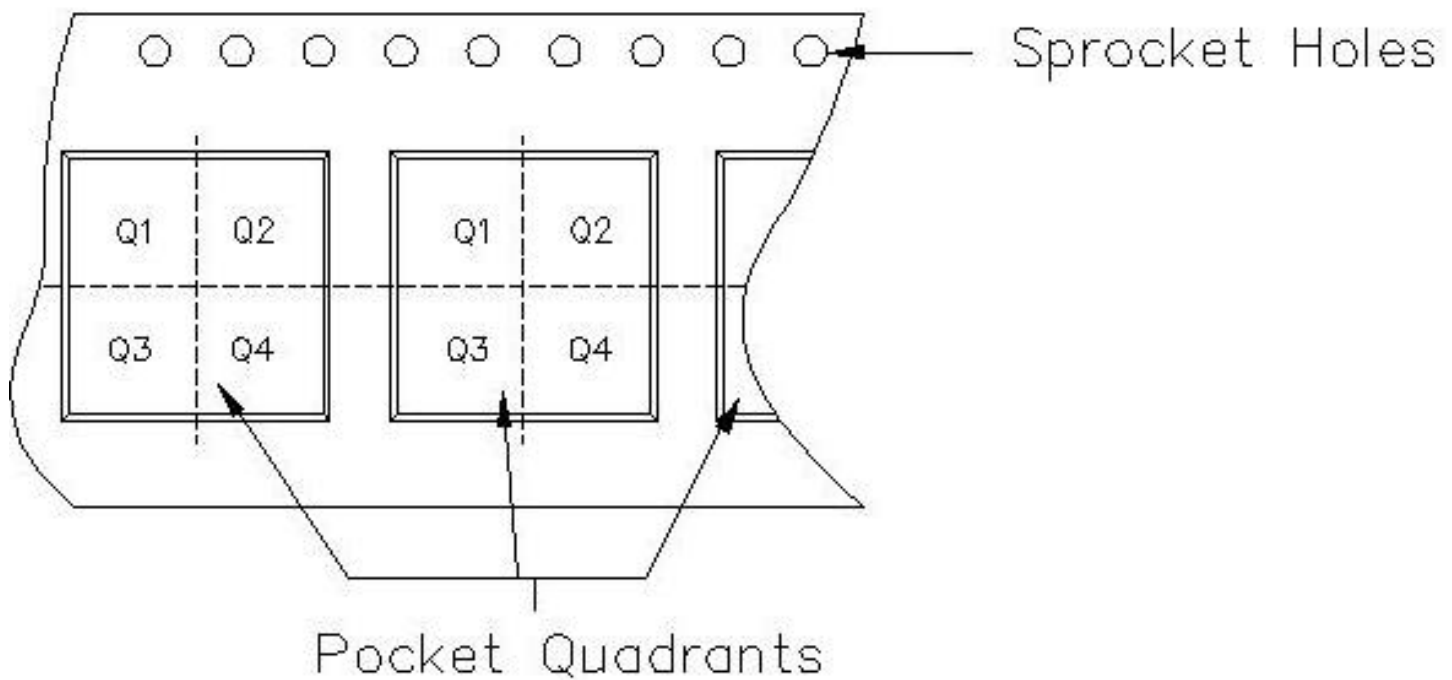
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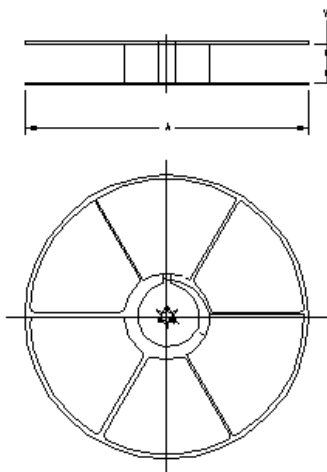
Carrier tape design is defined largely by the component length, width, and thickness.

A_o = Dimension designed to accommodate the component width.
B_o = Dimension designed to accommodate the component length.
K_o = Dimension designed to accommodate the component thickness.
W = Overall width of the carrier tape.
P = Pitch between successive cavity centers.



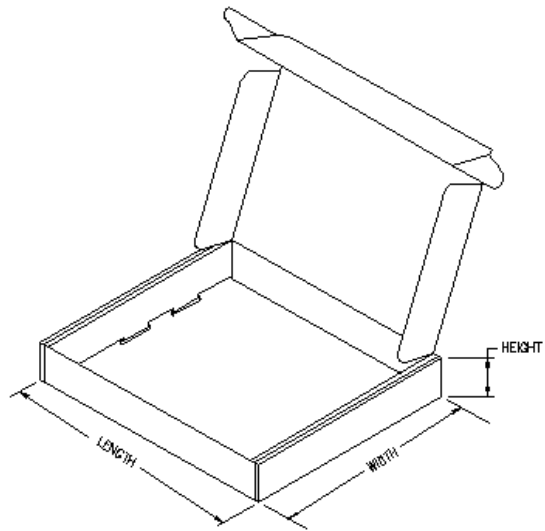
TAPE AND REEL INFORMATION

Device	Package	Pins	Site	Reel Diameter (mm)	Reel Width (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVT16244BDGGR	DGG	48	MLA	330	24	8.6	15.8	1.8	12	24	Q1
SN74LVT16244BDGVR	DGV	48	MLA	330	24	6.8	10.1	1.6	12	24	Q1
SN74LVT16244BDLR	DL	48	MLA	330	32	11.35	16.2	3.1	16	32	Q1
SN74LVT16244BGQLR	GQL	56	HIJ	330	16	4.8	7.3	1.45	8	16	Q1
SN74LVT16244BGRDR	GRD	54	HIJ	330	16	5.8	8.3	1.55	8	16	Q1
SN74LVT16244BZQLR	ZQL	56	HIJ	330	16	4.8	7.3	1.45	8	16	Q1
SN74LVT16244BZRDR	ZRD	54	HIJ	330	16	5.8	8.3	1.55	8	16	Q1



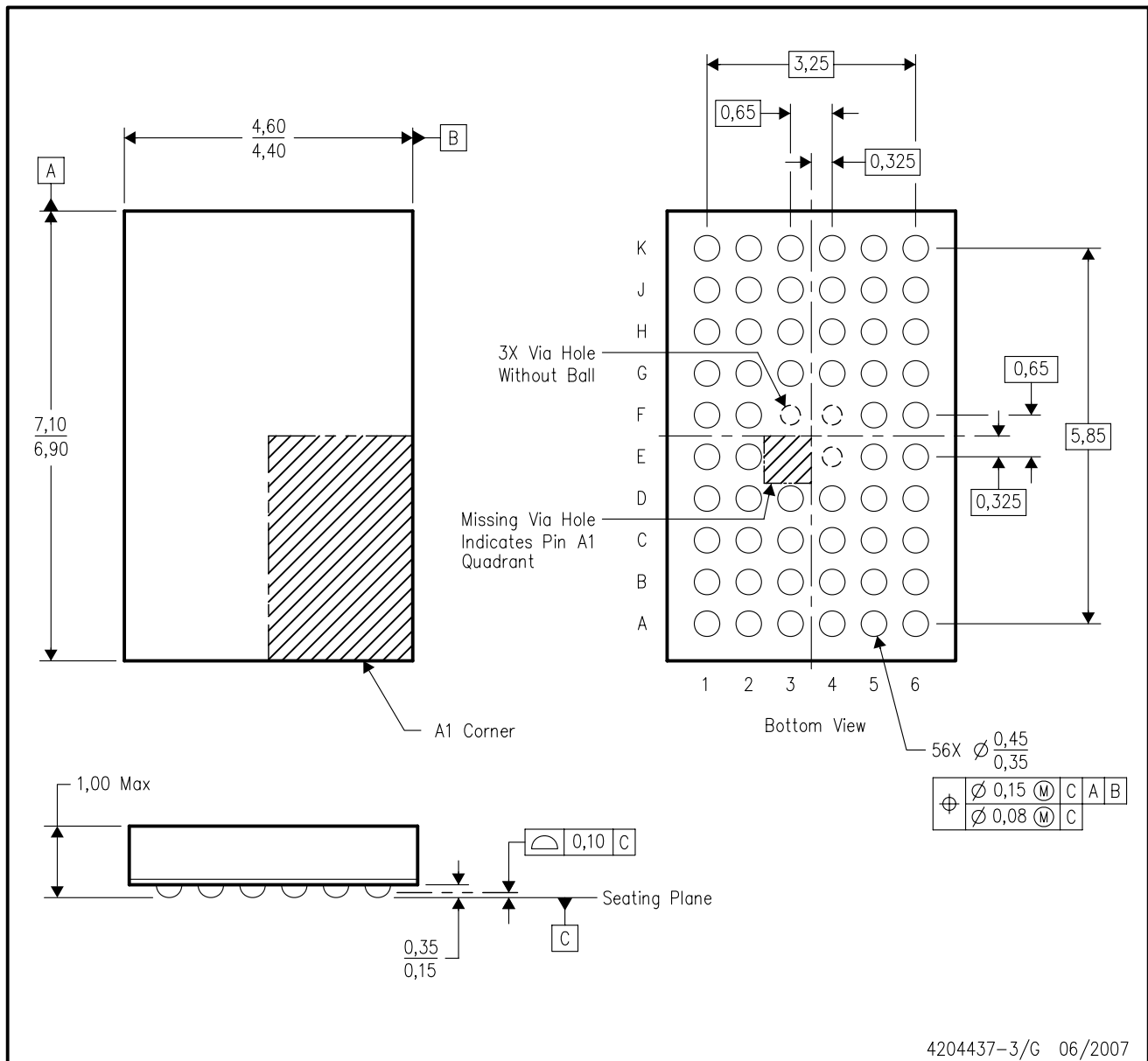
TAPE AND REEL BOX INFORMATION

Device	Package	Pins	Site	Length (mm)	Width (mm)	Height (mm)
SN74LVT16244BDGGR	DGG	48	MLA	333.2	333.2	31.75
SN74LVT16244BDGVR	DGV	48	MLA	333.2	333.2	31.75
SN74LVT16244BDLR	DL	48	MLA	336.6	342.9	41.3
SN74LVT16244BGQLR	GQL	56	HIJ	346.0	346.0	33.0
SN74LVT16244BGRDR	GRD	54	HIJ	346.0	346.0	33.0
SN74LVT16244BZQLR	ZQL	56	HIJ	346.0	346.0	33.0
SN74LVT16244BZRDR	ZRD	54	HIJ	346.0	346.0	33.0



ZQL (R-PBGA-N56)

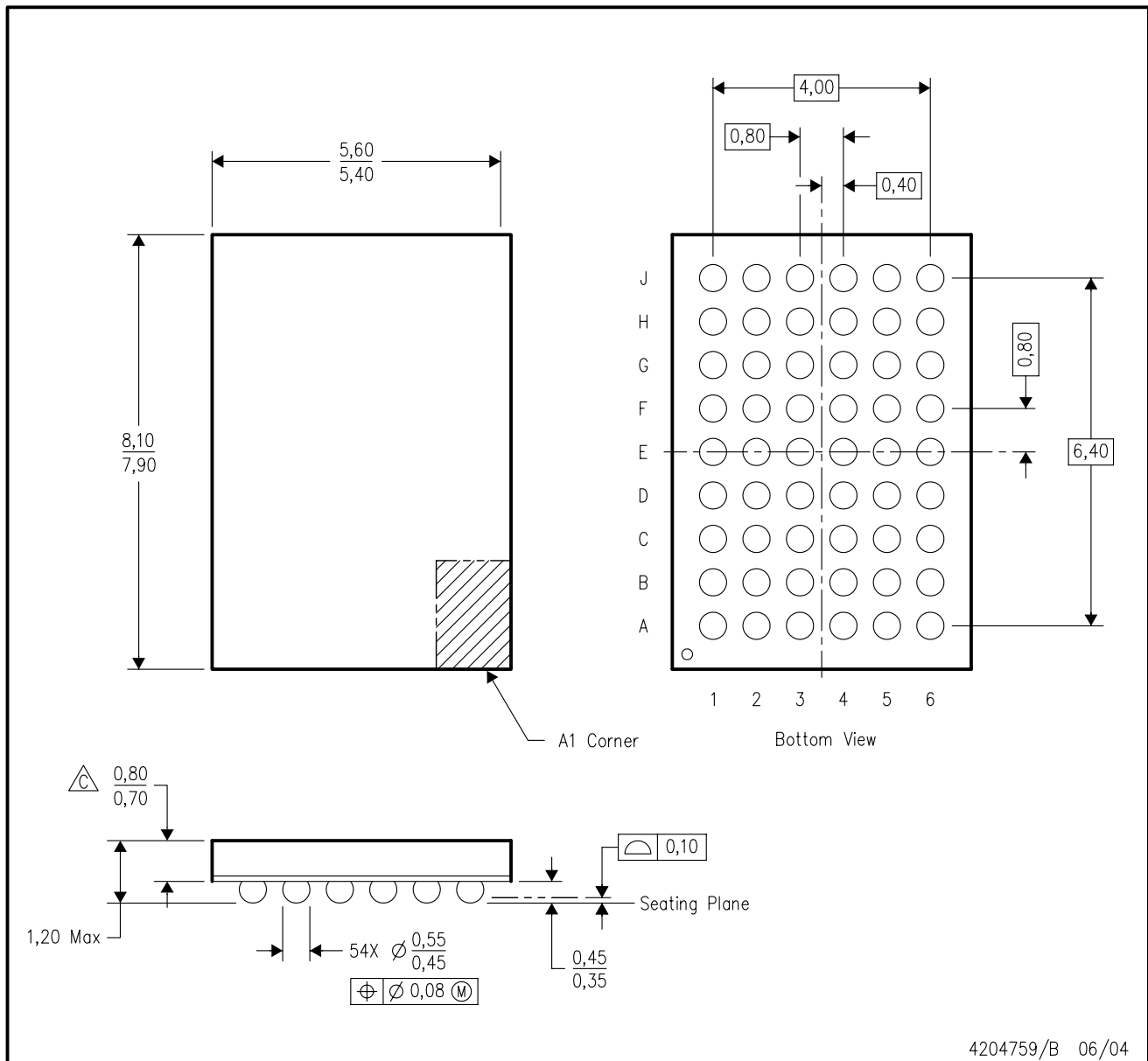
PLASTIC BALL GRID ARRAY



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Falls within JEDEC MO-285 variation BA-2.
 - D. This package is lead-free. Refer to the 56 GQL package (drawing 4200583) for tin-lead (SnPb).

GRD (R-PBGA-N54)

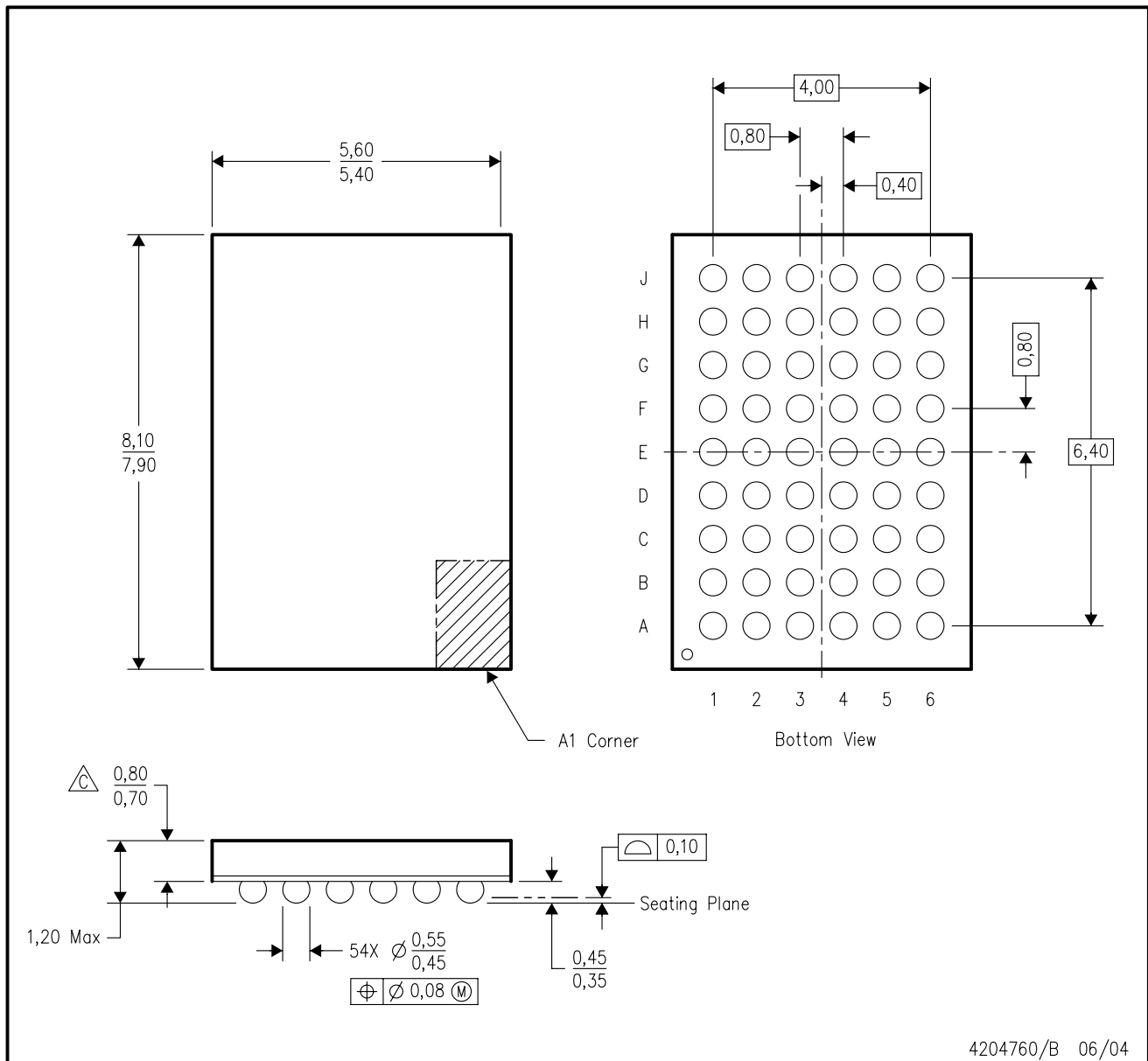
PLASTIC BALL GRID ARRAY



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - $\triangle C$ Falls within JEDEC MO-205 variation DD.
 - D. This package is tin-lead (SnPb). Refer to the 54 ZRD package (drawing 4204760) for lead-free.

ZRD (R-PBGA-N54)

PLASTIC BALL GRID ARRAY



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - \triangle Falls within JEDEC MO-205 variation DD.
 - D. This package is lead-free. Refer to the 54 GRD package (drawing 4204759) for tin-lead (SnPb).

DGV (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

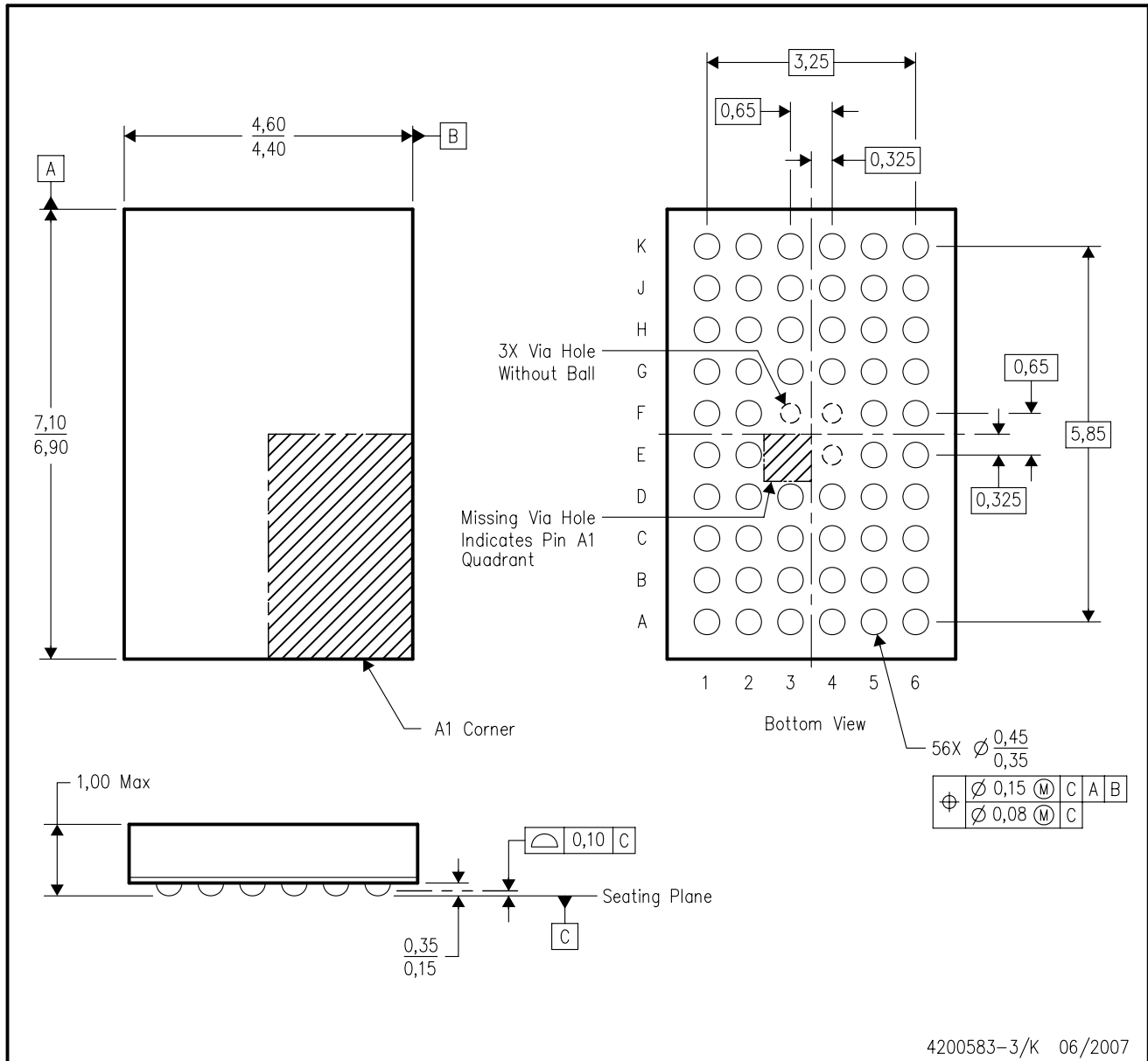
24 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
 D. Falls within JEDEC: 24/48 Pins – MO-153
 14/16/20/56 Pins – MO-194

GQL (R-PBGA-N56)

PLASTIC BALL GRID ARRAY

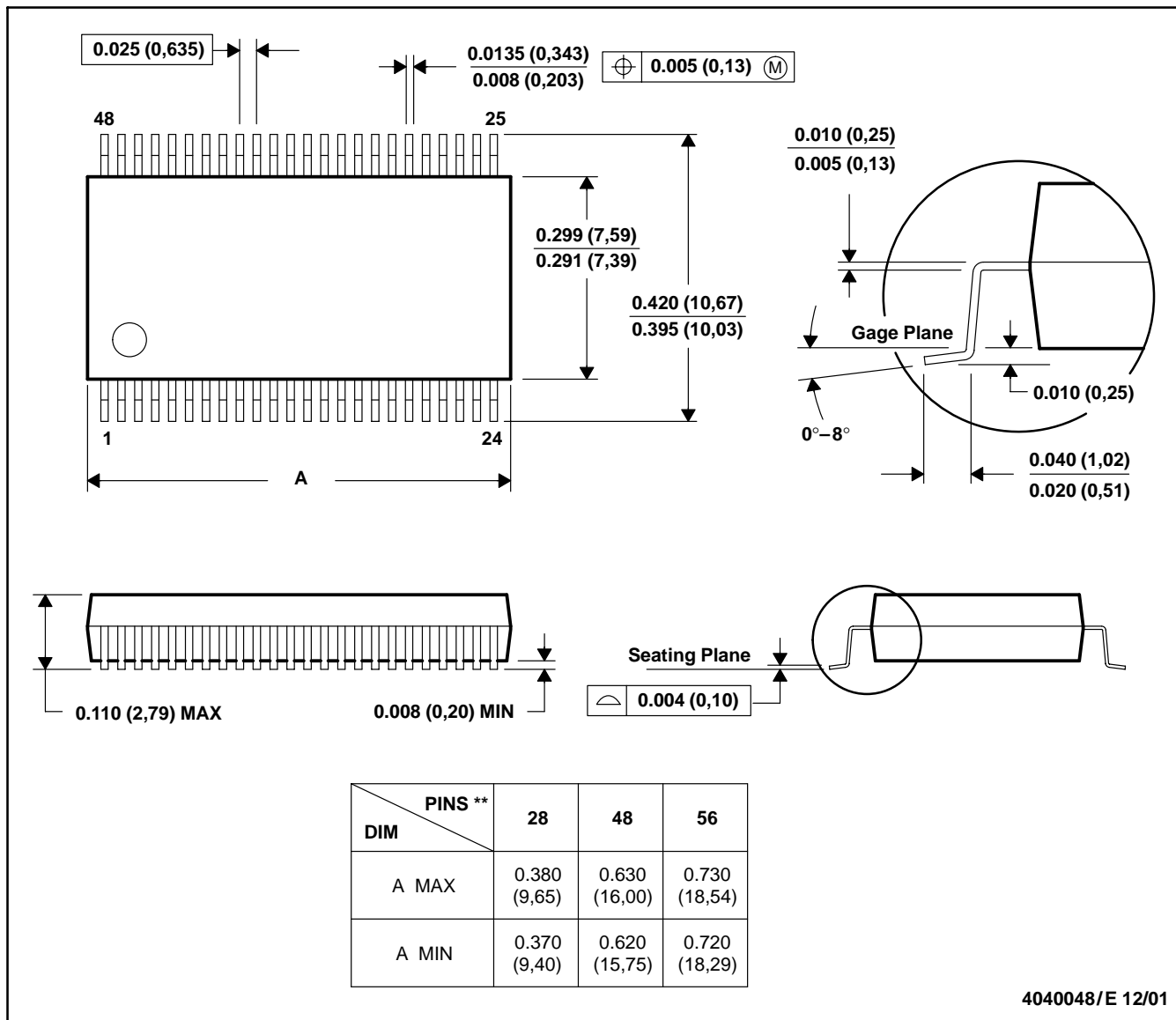


- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Falls within JEDEC MO-285 variation BA-2.
 - D. This package is tin-lead (SnPb). Refer to the 56 ZQL package (drawing 4204437) for lead-free.

DL (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 D. Falls within JEDEC MO-118

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

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